

NuKlean Reflow Oven Cleaner

Technical Data Sheet

Cleaning Solution for Burnt-On Flux Residues

Cleaning solution for burnt-on flux residues from wave soldering machines and reflow ovens. Effective at removing fluxes, no-clean fluxes, pastes, organic residues, adhesives, greases and oils.

Description:

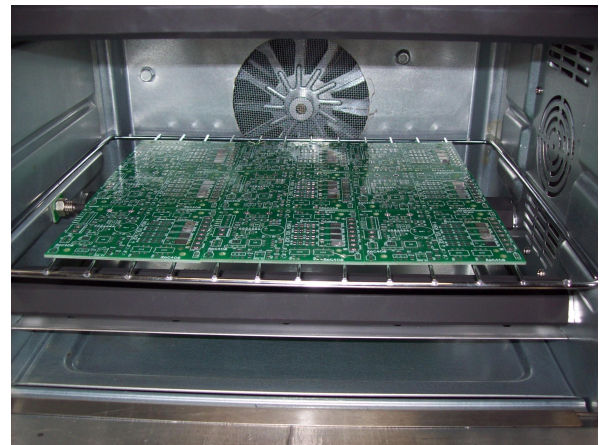
NuGeneration Technologies' NuKlean Reflow Oven Cleaner is a synergistic mixture of solvents used to remove tenacious burnt-on flux residues from all reflow and wave soldering machine surfaces including pallets, baffles, heating elements, clamps, chains, drive gears and housings. **NuKlean Reflow Oven Cleaner** is also highly effective at removing fluxes, no-clean fluxes, pastes, organic residues, adhesives, greases and oils from SMT and BGA circuit boards, connectors and components.

Characteristics:

NuKlean Reflow Oven Cleaner was formulated to be highly effective at removing evaporated fluxes and gas emissions from solder resist that soil the surfaces of reflow oven and wave soldering machines during reflow processes which can interfere with oven temperature profile consistency and overall performance. **NuKlean Reflow Oven Cleaner** is non flammable and can be used on cold or warm oven surfaces, though, use on very hot surfaces should be avoided as to not hinder the overall cleaning performance.

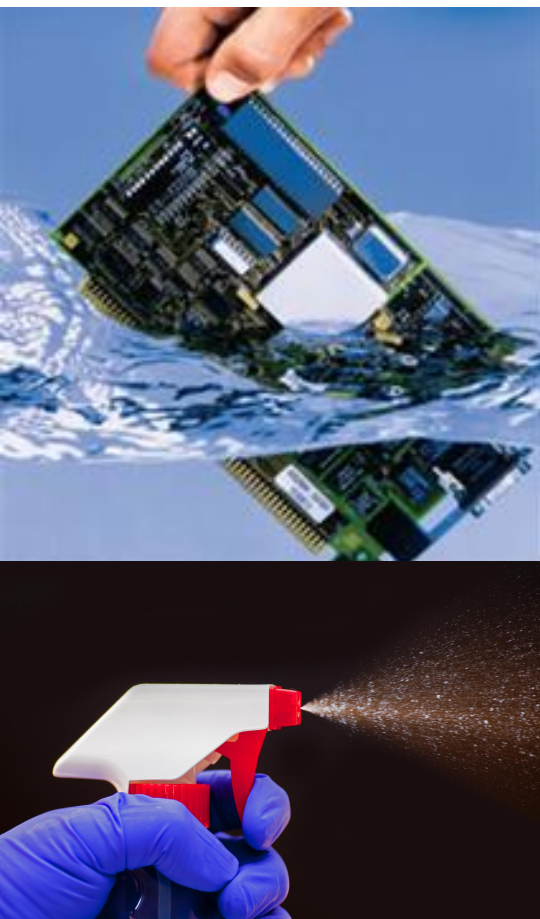
Directions for Use:

NuKlean Reflow Oven Cleaner can be used at 25-100% concentration, depending upon the desired use. For cleaning burnt-on fluxes from reflow oven and wave soldering oven surfaces, use at 50-100% concentration in a spray-and-wipe application on cold or warm oven surfaces. If cleaning fluxes, no-clean fluxes, pastes, organic residues, adhesives, greases or oils from SMT and BGA circuit boards, connectors and components, use at 25-50% at 25-60 °C (77-140 °C) for 5 seconds to 5 minutes in dip tank. The parameters can vary due to the type and extent of soils to be removed.



Product Benefits

- Easily removes burnt-on flux residues from all reflow and wave soldering oven surfaces
- Highly effective solution for removing fluxes, no-clean fluxes, pastes, organic residues, adhesives, greases and oils from SMT and BGA boards



Physical Properties

Use concentration (spray-and-wipe)	50-100% by volume
Use concentration (dip tank and ultrasonics)	25-50% by volume
Bulk Density	8.8 lbs/gal
Operating Temps	Ambient to 60 °C
Boiling Point	100 °C
pH, @100%	11.5
VOC (Concentrate)	94 g/L
Flash Point	> 94 °C
Toxic?	No
Leaves Residue?	No
Contains Ionics?	No

Availability: 1-gallon, 5-gallon and 55-gallon containers, and 275-gallon totes.

Shipment: UN2735 Amines, liquid, corrosive, n.o.s., 8, PG III, ERG #153

Storage: Keep out of direct sunlight. Keep from freezing. Store between 40 ° F - 120 °F.

Disposal: Dispose of in accordance with local, state, and federal regulations. For assistance with disposal contact NuGeneration Technologies at 888-99-NuGen or email: info@nugentec.com.

Regulatory: This product is classified and labeled according to the Globally Harmonized System (GHS).

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EMERGENCY OVERVIEW:

May cause severe skin burns and eye damage.

SAFETY:

Please make sure you have read and understand the product label and SDS before using this product. Avoid breathing vapors, spray or mists. Use only with adequate ventilation. Wash thoroughly after handling. Observe label precautions.